

Type 3502 Series

2W@70°C in 2010 size package

Key Features

Suitable for auto placement

Available from distribution

Terminal finish matte sn over ni barrier

Moisture sensitivity level - MSL1



TE Connectivity is pleased to introduce this thick film high power device, sister to our popular 3522 series, suitable for auto placement in volume and for most applications. Supplied as standard on 7 inch Reels of 2000 pieces per reel.

Note: SMD (Surface mount devices) resistors and inductors should be kept in their original packaging to protect them from ESD (Electrostatic Discharge). The full reels can be broken into smaller quantities, without exposing them to ESD, as long as the components are still in the plastic or paper tape. These resistors and inductors should not be removed from the plastic or paper tape unless they are in an ESD protected environment.

Characteristics – Electrical

Power Rating @ 70°C	2W
Resistance Range	1Ω ~ 10ΜΩ
Resistance Tolerance	±1%, ±5%
Temperature Coefficient of Resistance	1Ω~10Ω ≤± 200PPM/°C
(TCR)	10.1Ω~10MΩ ≤± 100PPM/°C
Max. Working Voltage	200V
Max. Overload Voltage	500V
Dielectric Withstanding Voltage	500V
Operating Temperature Range	-55°C ∼ 155°C

Resistors shall have a rated direct-current (DC) continuous working voltage or a approximate sine-wave root-mean-square (RMS) alternating-current (AC) continuous working voltage at commercial line frequency and waveform corresponding to the power rating, as determined from the following formula :

 $RCWV = \sqrt{P \times R}$

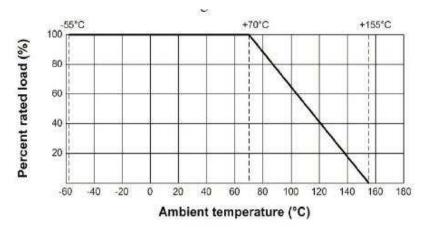
Where the calculated RCWV is greater than the stated Max. Working Voltage, the Max. Working Voltage will apply.

Dimensions in millimetres unless otherwise specified Dimensions Shown for reference purposes only. Specifications subject to change

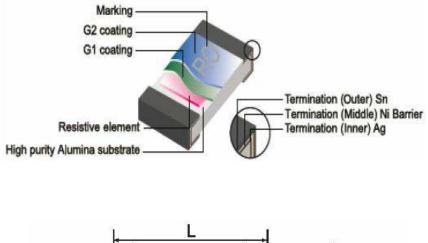


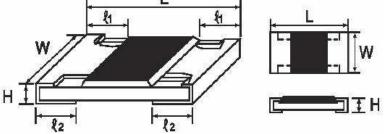
Power Rating and Derating

Resistors shall have a power rating based on continuous load operation at an ambient temperature of 70 $^{\circ}\text{C}$. For temperature in excess of 70 $^{\circ}\text{C}$, The load shall derate as shown in chart below.



Construction and Dimensions:





Turne	Dimensions (mm)						
Туре	L	W	Н	e 1	€2		
3502	5.00 ± 0.10	2.50 ± 0.15	1.10 ± 0.10	0.60 ± 0.25	0.50 ± 0.20		

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Performance Specification

Characteristics	Limits	Test Methods		
		(JIS C 5201-1)		
Dielectric Withstanding	No evidence of flashover,	4.7 Clamped in the trough of a		
Voltage	mechanical damage, arcing	90°C metallic v-block and shall be		
_	or insulation break down	testec	l at ac potential	
		respe	ctively specified ir	the type
		-	-70 seconds	/
Temperature	1Ω~10Ω ≤± 200PPM/°C	4.8 Natural resistance change per		
Coefficient	$10.1\Omega^{-10M\Omega} \leq \pm 100PPM/^{\circ}C$			
Coefficient	10.112 101012 ST 100FF1017 C	temp. degree centigrade.		
		R2-R1		
		R1(t2-t1) x 106 (PPM/°C)		
			sistance value at	room
			erature (T1)	
			sistance value at	room
			plus 100 °C(T2)	
		Test p	attern: room tem	р. (Т1),
		room	temp. +100°C(T2)	
Short Time Overload	Resistance change rate is:	4.13 P	ermanent resista	nce
	± 5% (2.0% + 0.1Ω) Max.	chang	e after the applica	ation of a
	± 1% (1.0% + 0.1Ω) Max.	poten	tial of 2.5 times R	CWV for 5
		seconds		
Solderability	95 % coverage Min.	Wave Solder:		
,	C C	Test temperature of solder:		
		245°C ±3°C dipping time in solder : 2-3 seconds.		
		Reflow		
			PEAN VALUE TEMPERATURE: 245°C - 250°C	
		250	245°C - 250°C	7
		200	TOOTO WARM-UP TIME	\land
		150	180°C	
		Reference -	90±30s	
		100	20±10s	
		50	HOT UP TIME SOLDER	time λ
Soldering heat	Resistance change rate is:	4.18 Dip the resistor into a solder		
	± (1.0%+0.05Ω) Max.	bath having a temperature of		
		260°C±3°C and hold it for 10±1		
		seconds.		
Temperature Cycling	Resistance change rate is:	4.19 Resistance change after		
	± 5% (1.0% + 0.1Ω) Max.	continuous 5 cycles for duty cycl		duty cycle
	± 1% (0.5% + 0.1Ω) Max.	specified below:		
		Step	Temp.	Time
		1	-55°C ± 3°C	30m
		2	Room temp.	10~15m
		3	+155°C ± 2°C	30m
		4	Room temp.	10~15m
		<u>⊢ ·</u>		10 15111
Humidity	Resistance change rate is:	1 24 7	emporary resista	100
mannunty	Resistance change rate is: $\pm 5\% (3.0\% + 0.1\Omega)$ Max.	4.24 Temporary resistance		
		change after 240 hours exposure		
	± 1% (0.5% + 0.1Ω) Max.		umidity test cham	
			olled at 40±2°C an	a 90-95%
		relative humidity		

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Performance Specification (Cont.)

Characteristics	Limits	Test Methods	
		(JIS C 5201-1)	
Load life in humidity	Resistance change rate is:	7.9 Resistance change after 1,000	
	± 5% (3.0% + 0.1Ω) Max.	hours (1.5 hours "on", 0.5 hour	
	± 1% (1.0% + 0.1Ω) Max.	"off") at RCWV in a humidity	
		chamber controlled at 40°C ± 2°C	
		and 90 to 95 % relative humidity	
Load Life	Resistance change rate is:	4.25.1 Permanent resistance	
	± 5% (3.0% + 0.1Ω) Max.	change after 1,000 hours	
	± 1% (1.0% + 0.1Ω) Max.	operating at RCWV, with duty	
		cycle of (1.5 hours "on", 0.5 hour	
		"off") at 70°C ± 2°C ambient	
Terminal bending	Resistance change rate is:	4.33 Twist of Test Board:	
	± (1.0% + 0.05Ω) Max.	Y/X = 3/90 mm for 60 seconds	

Marking

A. 4 digit marking for E-96 series:

*The first 3 digits are significant figures of resistance and the 4th digit denoted number of zeros.

Ex.**1273**127KΩ*For ohmic values below 100 Ω, letter "R" is for decimal point.

Ex. 49R9	49.9Ω
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B. 3 digit marking for E-24 series:

*The first 2 digits are significant figures of resistance and the 3rd digit denoted number of zeros

 Ex.
 124 120KΩ

 *For ohmic values below 10 Ω, letter "R" is for decimal point

Ex. 4R7



2.00

Soldering

PCB Plan (mm)

4 layers PCB specification:
1) Outside 2 layers (Top and Bottom)
with copper foil thickness at 2oz.
2) Inside 2 layers (Middle layers)
with copper foil thickness at 4 oz.

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For Email, phone or live chat, go to: www.te.com/help

3.00



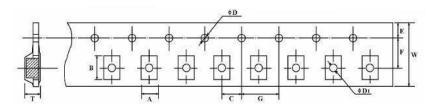
Soldering

Reflow solder profile



Packaging

Tape and Reel



(mm)

A ±0.1	B ±0.1	C±0.15	ØD+0.1 -0	E±0.1	F±0.15	G ±0.1	W ±0.3	ØD1 ±0.1	T ± 0.1
2.65	5.25	2.0	1.5	1.75	5.5	4.0	12	1.0	1.35

Peeling Strength of Top Cover Tape

Test Condition: 0.1 to 0.7 N at a peel-off speed of 300 mm / min.

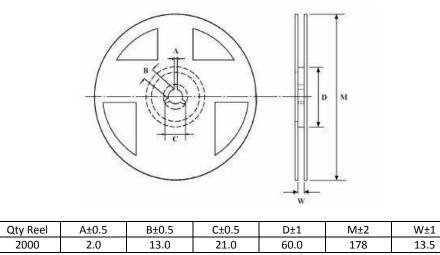


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Reel Dimensions



Environment Related Substance

This product complies to EU RoHS directive, EU PAHs directive, EU PFOS directive and Halogen free.

Storage Condition

The performance of these products, including the solderability, is guaranteed for a year from the date of arrival at your company, provided that they remain packed as they were when delivered and stored at a temperature of $25^{\circ}C \pm 10^{\circ}C$ and a relative humidity of 60%RH $\pm 10\%$ RH, chemical and dust free atmosphere.

Even within the above guarantee periods, do not store these products in the following conditions:

1. In salty air or in air with a high concentration of corrosive gas, such as Cl2, H2S, NH3, SO2, or NO2

2. In direct sunlight

How To Order

3502	1R0	F	Т
Common Part	Resistance Value	Tolerance	Pack Style
3502 – 2W 2010 Resistor	1Ω - 1R0 100Ω - 100R 1KΩ - 1K0	F — 1% J — 5%	T- 2000 per reel

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Mouser Electronics

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TE Connectivity:

350218KFT